

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 10-090893

(43)Date of publication of application : 10.04.1998

(51)Int.Cl.

G03F 7/038
 C08L101/02
 C09D 5/00
 C09D133/06
 G03F 7/004
 // H05K 3/28

(21)Application number : 08-243450

(71)Applicant : RIKAGAKU KENKYUSHO

(22)Date of filing : 13.09.1996

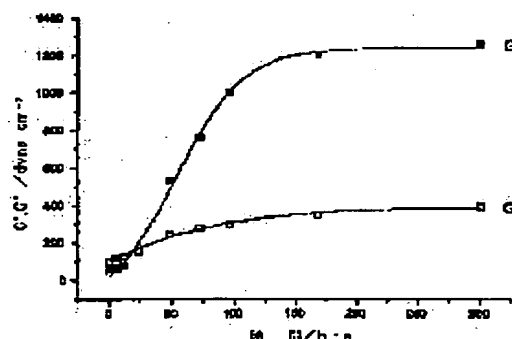
(72)Inventor : TAJIMA YUUSUKE
 ISHII TADAHIRO
 TAKEUCHI KAZUO

(54) PHOTSENSITIVE RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a photosensitive resin compsn. using a relatively small amt. of Fullerene and curable with visible light.

SOLUTION: This photosensitive resin compsn. contains Fullerene and a high molecular compd. having a functional group capable of reacting with the Fullerene under irradiation with visible light. A negative type image element is formed as follows; a layer of this compsn. is formed and irradiated with visible light through a photomask having a visible radiation transmitting pattern, the irradiated part in the layer is cured and the uncured part in the layer is removed to form a patterned resist film. A device is produced by etching an image forming layer through the resist film and then removing the resist film.



LEGAL STATUS

[Date of request for examination] 22.07.1998

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 2878654

[Date of registration] 22.01.1999

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office

BEST AVAILABLE COPY